



TABLE 2

	Comparative Example										
	1	2	3	4	5	6	7	8	9	10	11
Phenol biphenylaralkyl type epoxy resin	7.4	9.4		7.4	7.5	7.6	7.35	7.4	7.35	7.4	7.35
Biphenyl type epoxy resin											
Cresol novolac type epoxy resin		6.9									
Phenol biphenylaralkyl resin	5.5			5.5	5.52	5.65	5.5	5.5	5.5	5.5	5.5
Phenolaralkyl resin		6.0									
Phenol novolac resin	3.5										
Spherical fused silica	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
γ-Glycidyl/pnpyltrimethoxysilane	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4
7-Mercapto pro pyrtrimethoxysilane				0.4							
Triphenylphosphine	0.2	0.15	0.15	0.2	0.06	0.2	0.2	0.2	0.2	0.2	
DBU											0.2
Curing accelerator of formula C7)											0.25
Curing accelerator of formula C8)											0.25
2,3-Dihydronaphthalene				0.05	0.05			0.05			
1,2-Dihydroxynaphthalene											
Catechol											
Pyrogallol											
1,6-Dihydroxynaphthalene									0.05		
Resorcinol											
Cansuba wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)	80	76	71	62	114	76	78	81	68	89	77
Curing torque ratio (%)	65	67	70	62	7	56	65	64	57	B5	89
Solder resistance-cracking	4	2	chip	3		9	5	4	4	2	3
Chip delamination		10	exposure	0	Poor	0	0	0	0	0	0
Internal crack	0	V-0	HB	V-0	Poor Releasing	V-0	V-0	V-0	V-0	V-0	V-0
Fire retardancy											